

### Rad-Hard 16 Channel CMOS Analog Multiplexer with High-Z Analog Input Protection

The HS-1840ARH is a radiation hardened, monolithic 16 channel multiplexer constructed with the Intersil Rad-Hard Silicon Gate, bonded wafer, Dielectric Isolation process. It is designed to provide a high input impedance to the analog source if device power fails (open), or the analog signal voltage inadvertently exceeds the supply by up to  $\pm 35V$ , regardless of whether the device is powered on or off. Excellent for use in redundant applications, since the secondary device can be operated in a standby unpowered mode affording no additional power drain. More significantly, a very high impedance exists between the active and inactive devices preventing any interaction. One of sixteen channel selection is controlled by a 4-bit binary address plus an Enable-Inhibit input which conveniently controls the ON/OFF operation of several multiplexers in a system. All inputs have electrostatic discharge protection.

The HS-1840ARH is processed and screened in full compliance with MIL-PRF-38535 and QML standards. The device is available in a 28 lead SBDIP and a 28 lead Ceramic Flatpack.

**Specifications for Rad Hard QML devices are controlled by the Defense Supply Center in Columbus (DSCC). The SMD numbers listed here must be used when ordering.**

**Detailed Electrical Specifications for these devices are contained in SMD 5962-95630. A "hot-link" is provided on our homepage for downloading.**  
<http://www.intersil.com/spacedefense/space.htm>

### Features

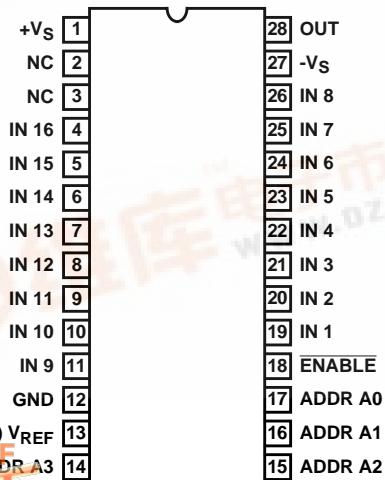
- Electrically Screened to SMD # 5962-95630
- QML Qualified per MIL-PRF-38535 Requirements
- Pin-to-Pin for Intersil's HS-1840RH and HS-1840/883S
- Improved Radiation Performance
  - Gamma Dose ( $\gamma$ )  $3 \times 10^5$  RAD(Si)
- Improved  $r_{DS(ON)}$  Linearity
- Improved Access Time 1.5 $\mu$ s (Max) Over Temp and Post Rad
- High Analog Input Impedance 500M $\Omega$  During Power Loss (Open)
- $\pm 35V$  Input Over Voltage Protection (Power On or Off)
- Dielectrically Isolated Device Islands
- Excellent in Hi-Rel Redundant Systems
- Break-Before-Make Switching
- No Latch-Up

### Ordering Information

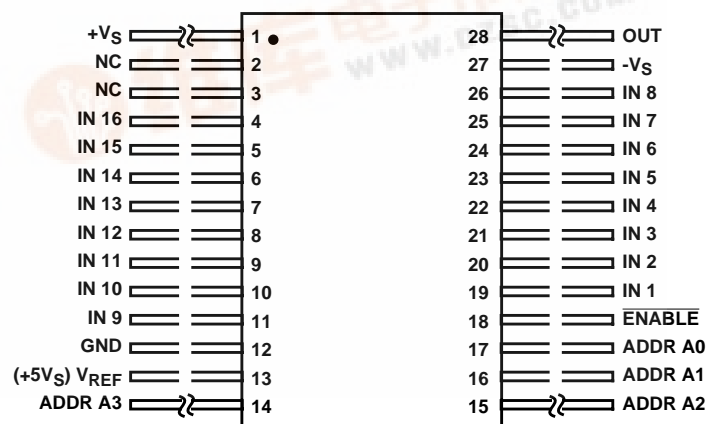
ORDERING NUMBER	INTERNAL MKT. NUMBER	TEMP. RANGE (°C)
5962F9563002QXC	HS1-1840ARH-8	-55 to 125
5962F9563002QYC	HS9-1840ARH-8	-55 to 125
5962F9563002V9A	HS0-1840ARH-Q	25
5962F9563002VXC	HS1-1840ARH-Q	-55 to 125
5962F9563002VYC	HS9-1840ARH-Q	-55 to 125
HS1-1840ARH/PROTO	HS1-1840ARH/PROTO	-55 to 125
HS9-1840ARH/PROTO	HS9-1840ARH/PROTO	-55 to 125

### Pinouts

HS1-1840ARH (SBDIP) CDIP2-T28  
TOP VIEW

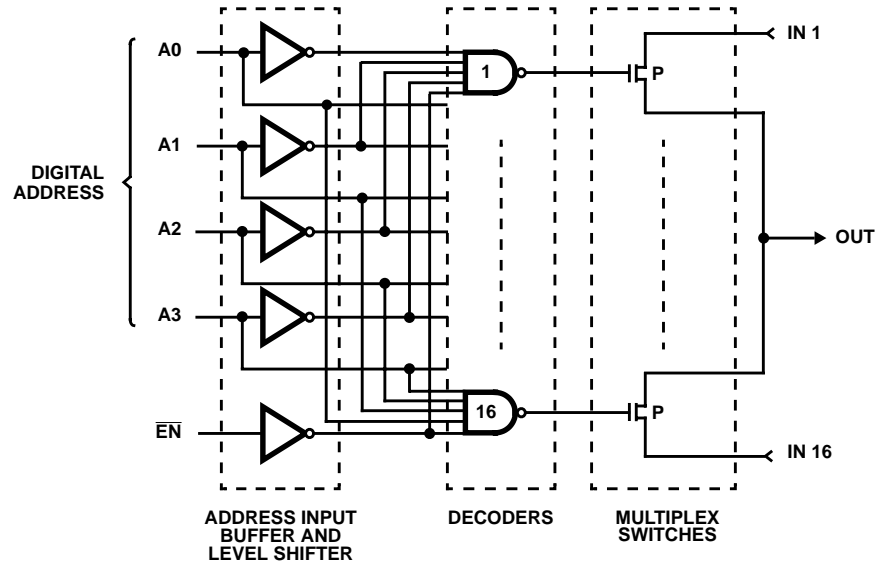


HS9-1840ARH (FLATPACK) CDFP3-F28  
TOP VIEW



# HS-1840ARH

## Functional Diagram

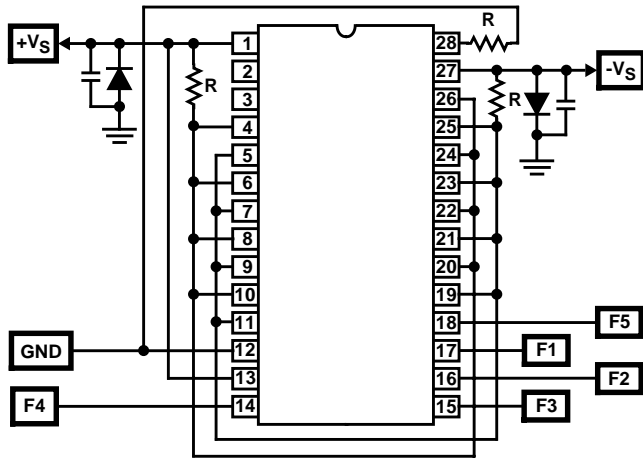


TRUTH TABLE

A3	A2	A1	A0	$\overline{EN}$	"ON" CHANNEL
X	X	X	X	H	None
L	L	L	L	L	1
L	L	L	H	L	2
L	L	H	L	L	3
L	L	H	H	L	4
L	H	L	L	L	5
L	H	L	H	L	6
L	H	H	L	L	7
L	H	H	H	L	8
H	L	L	L	L	9
H	L	L	H	L	10
H	L	H	L	L	11
H	L	H	H	L	12
H	H	L	L	L	13
H	H	L	H	L	14
H	H	H	L	L	15
H	H	H	H	L	16

## HS-1840ARH

### Burn-In/Life Test Circuits



**NOTES:**

$V_{S+} = +15.5V \pm 0.5V$ ,  $V_{S-} = -15.5V \pm 0.5V$ .

$R = 1k\Omega \pm 5\%$ .

$C_1 = C_2 = 0.01\mu F \pm 10\%$ , 1 each per socket, minimum.

$D_1 = D_2 = 1N4002$ , 1 each per board, minimum.

Input Signals: square wave, 50% duty cycle, 0V to 15V peak  $\pm 10\%$ .

$F1 = 100kHz$ ;  $F2 = F1/2$ ;  $F3 = F1/4$ ;  $F4 = F1/8$ ;  $F5 = F1/16$ .

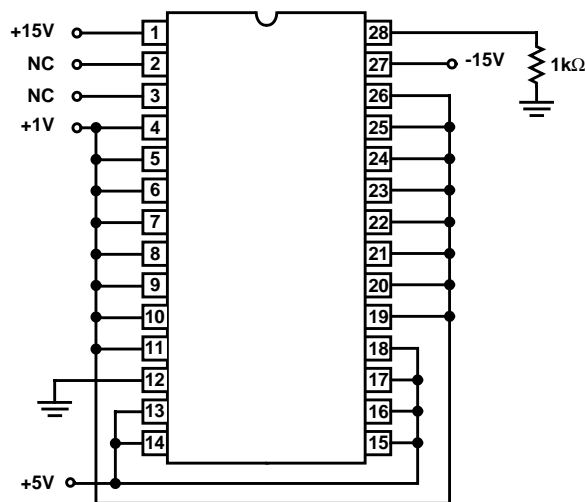
**FIGURE 1. DYNAMIC BURN-IN AND LIFE TEST CIRCUIT**

**NOTES:**

1. The above test circuits are utilized for all package types.
2. The Dynamic Test Circuit is utilized for all life testing.

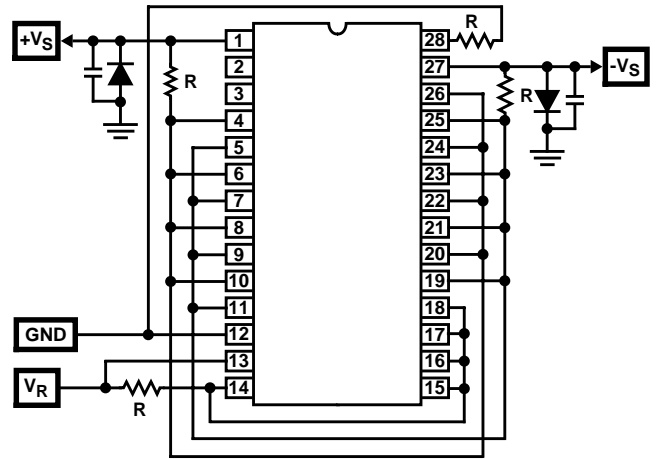
### Irradiation Circuit

#### HS-1840ARH



**NOTE:**

3. All irradiation testing is performed in the 28 lead CERDIP package.



**NOTES:**

$R = 1k\Omega \pm 5\%$ ,  $1/4W$ .

$C_1 = C_2 = 0.01\mu F$  minimum, 1 each per socket, minimum.

$V_{S+} = 15.5V \pm 0.5V$ ,  $V_{S-} = -15.5V \pm 0.5V$ ,  $V_R = 15.5 \pm 0.5V$ .

**FIGURE 2. STATIC BURN-IN TEST CIRCUIT**

# HS-1840ARH

## Die Characteristics

### DIE DIMENSIONS:

(2820 $\mu$ m x 4080 $\mu$ m x 483 $\mu$ m  $\pm$ 25.4 $\mu$ m)  
111 mils x 161 mils x 19 mils  $\pm$ 1 mil

### INTERFACE MATERIALS:

#### Glassivation:

Type: PSG (Phosphorus Silicon Glass)  
Thickness: 8.0k $\text{Å}$   $\pm$ 1k $\text{Å}$

#### Top Metallization:

Type: AlSiCu  
Thickness: 16.0k $\text{Å}$   $\pm$ 2k $\text{Å}$

#### Backside Finish:

Silicon

### ASSEMBLY RELATED INFORMATION:

#### Substrate Potential:

Unbiased (DI)

#### ADDITIONAL INFORMATION:

#### Worst Case Current Density:

Modified SEM

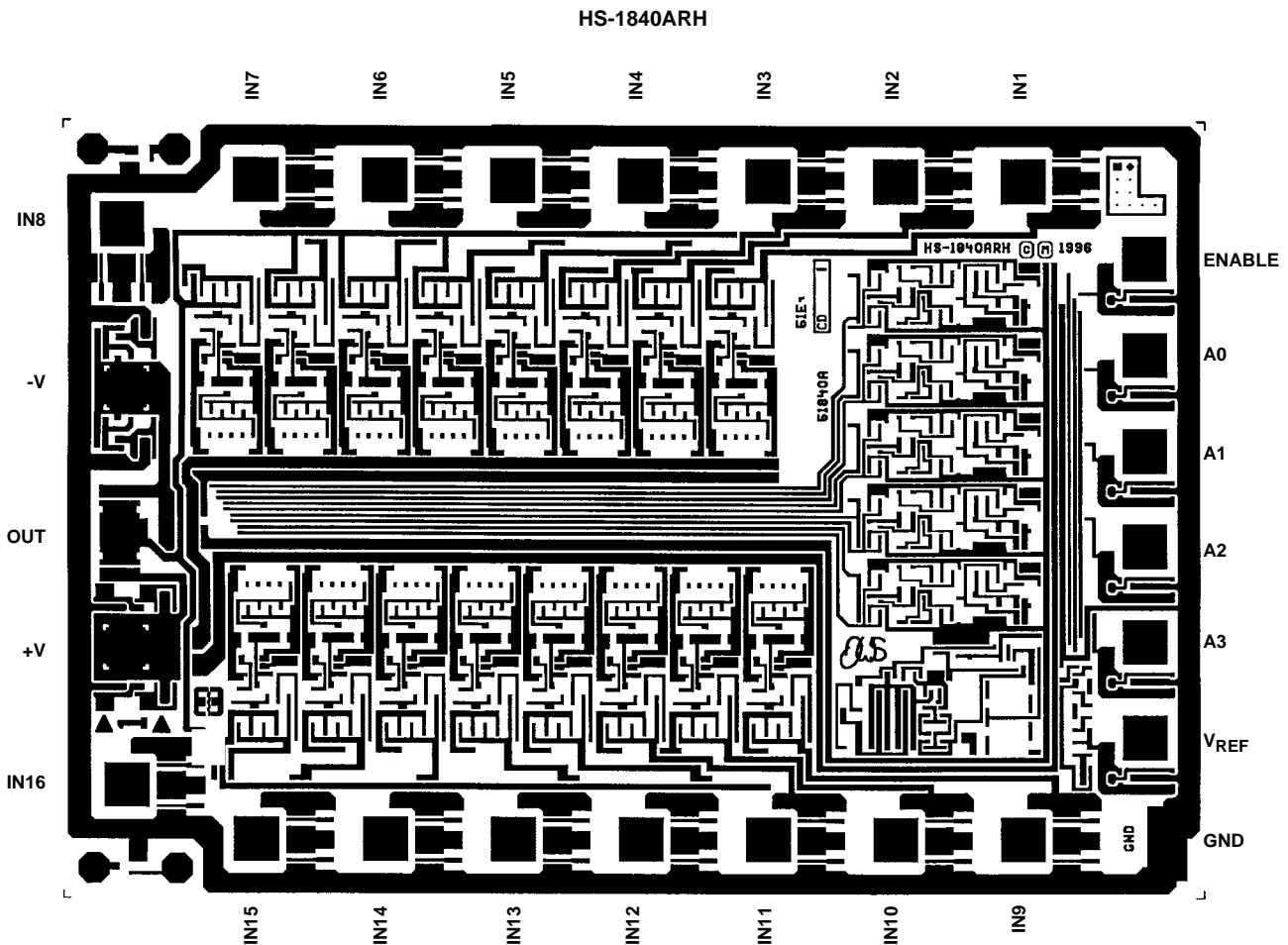
#### Transistor Count:

407

#### Process:

Radiation Hardened Silicon Gate,  
Bonded Wafer, Dielectric Isolation

## Metallization Mask Layout



All Intersil semiconductor products are manufactured, assembled and tested under ISO9000 quality systems certification.

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